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## Description

### Features.

- ◆ Super high Flux output and high Luminance
- ◆ Designed for high current operation
- ◆ Low thermal resistance:12°C/W
- ◆ SMT solder bility
- ◆ RoHS compliant

### Applications.

- ◆ General Illumination
- ◆ Outdoor & Indoor architectural lighting
- ◆ Decorative lighting
- ◆ Portable lighting and Reading lighting
- ◆ Traffic signaling

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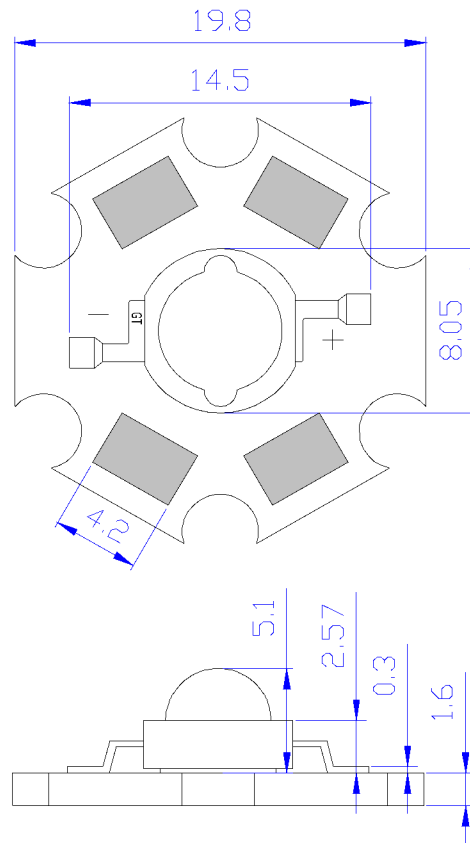
Soldering Condition

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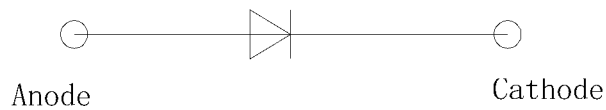
## Outline Dimensions

### 1、 Dome Type



### 2、 Circuit diagram

INTERNAL CIRCUIT DIAGRAM



#### Notes

1. All dimensions are in millimeters.(tolerance:±0.2)
2. Dimension Scale:1:1

\*The appearance and specifications of the product may be changed for improvement without notice.

## Parameters

### Electrical-Optical Characteristics at IF=750mA, Ta=25°C

Parameter	Symbol	Min	Typ	Max	Unit
Luminous Flux	$\phi_v$	240	~	260	lm
Correlated Color Temperature	CCT	6500	~	7000	K
CRI	Ra	60	~	90	~
Forward Voltage	V <sub>F</sub>	3.5	~	4.5	V
Power Dissipation	P <sub>D</sub>	2.63	~	3.38	W
View Angle	2 $\theta$ 1/2	~	120	~	deg.
Thermal Resistance	R $\theta$ J-B	~	12	~	°C/W

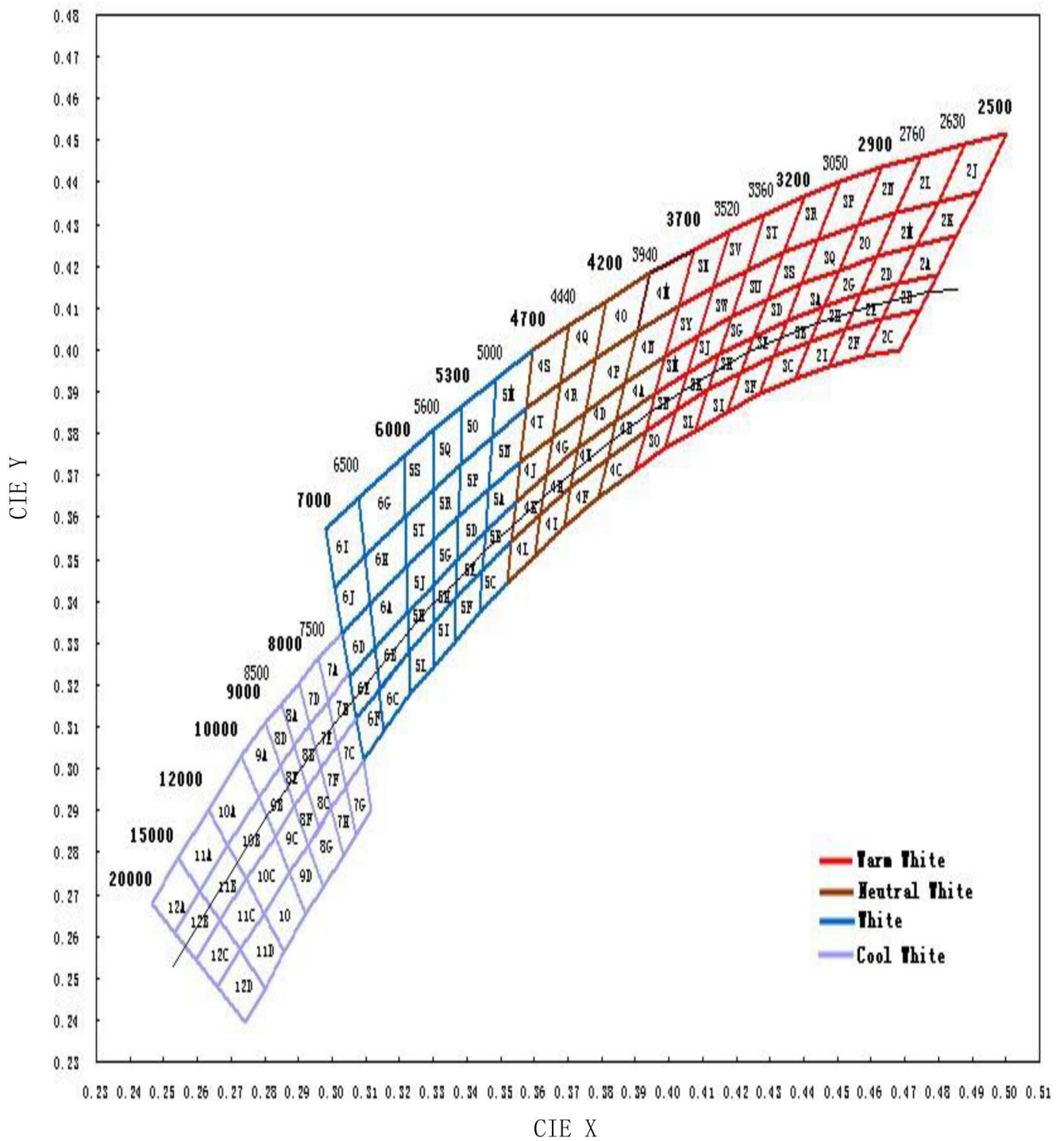
### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Forward Current	I <sub>F</sub>	750	mA
Junction Temperature	T <sub>j</sub>	115	°C
Operating Temperature	T <sub>opr</sub>	-40~+60	°C
Storage Temperature	T <sub>stg</sub>	0~+60	°C
ESD Sensitivity	~	±2,000V HBM	~
Temperature Coefficient of voltage	~	-5	mV/°C
DC Pulse Current(@ 1 KHz,10% duty cycle)	I <sub>FP</sub>	1000	mA
Reverse Voltage	V <sub>R</sub>	Not designed for reverse operation	

#### \*Notes

1. Tolerance of Luminous Flux is ±3%.
2. Tolerance of Forward Voltage is ±0.1V.

## White Bining Information

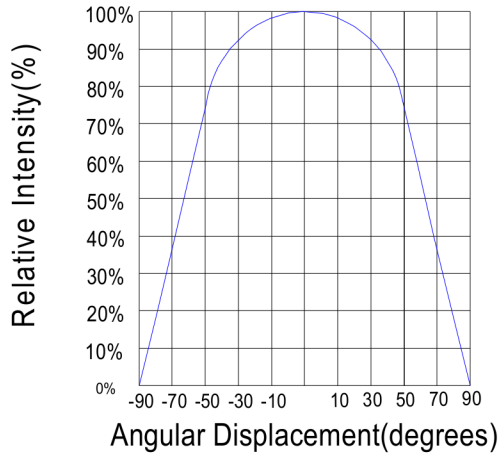


**\*Notes**

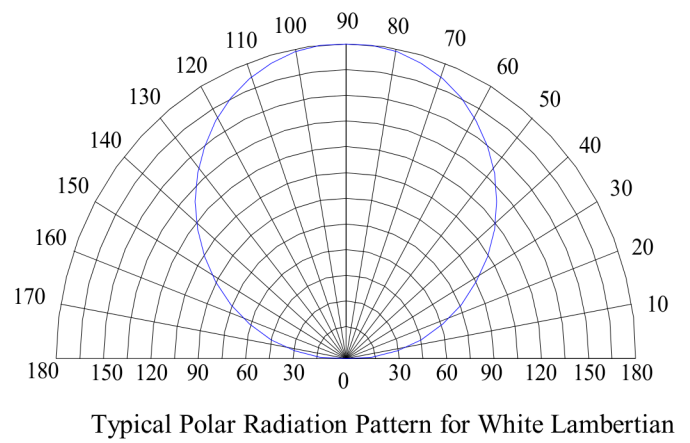
The black line represents the blackbody locus on CIE 1931 graph.

# Typical Characteristic Curves(1)

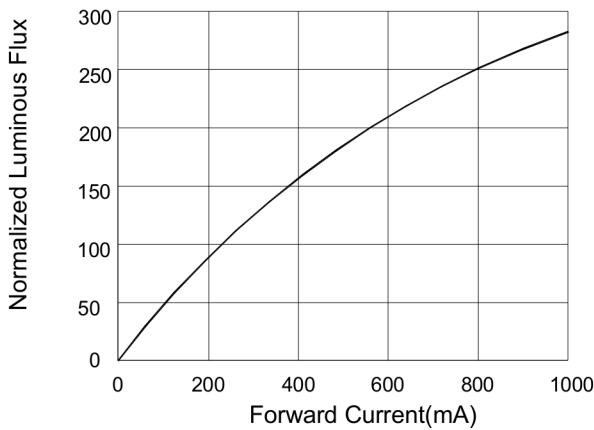
## 1. Typical Light Distribution Curve



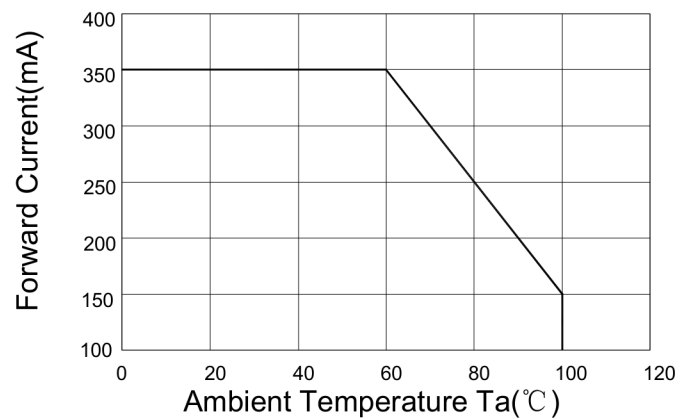
## 2. Typical Light-Emitting Angle Radiation Pattern



## 3. Forward Current vs. Relative Luminous Flux Curve

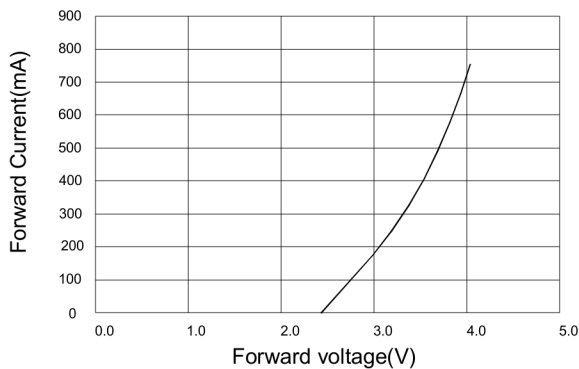


## 4. Forward Current Derating Curve, Derating based on $T_{max}=125^{\circ}C$

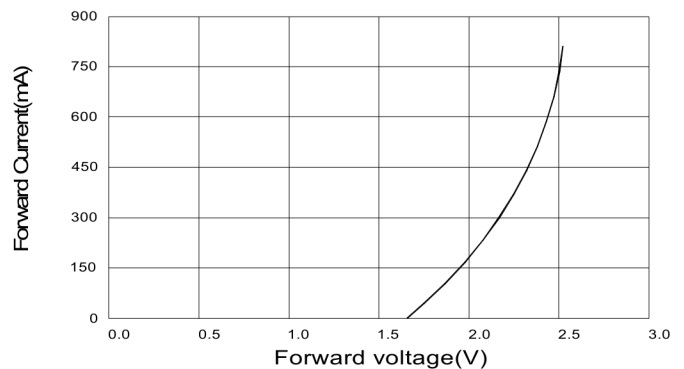


## 5. Electrical Characteristics Curve

### 5-1. White, Royal Blue, Blue, Green

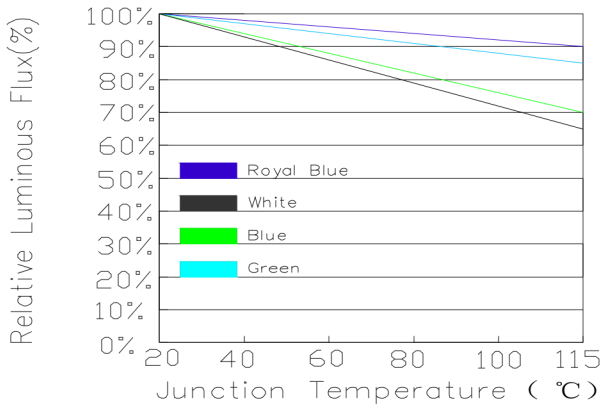


### 5-2. Amber, Red

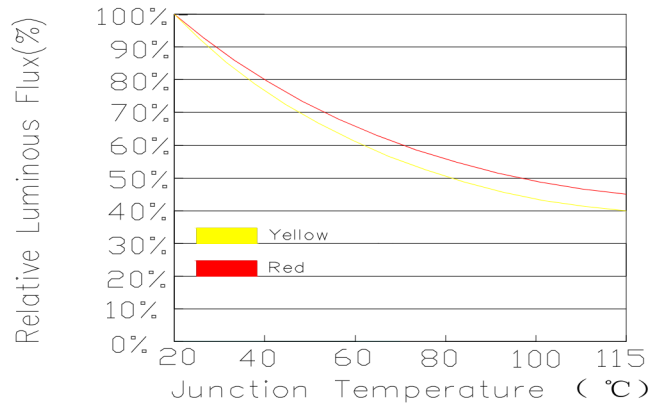


## Typical Characteristic Curves(2)

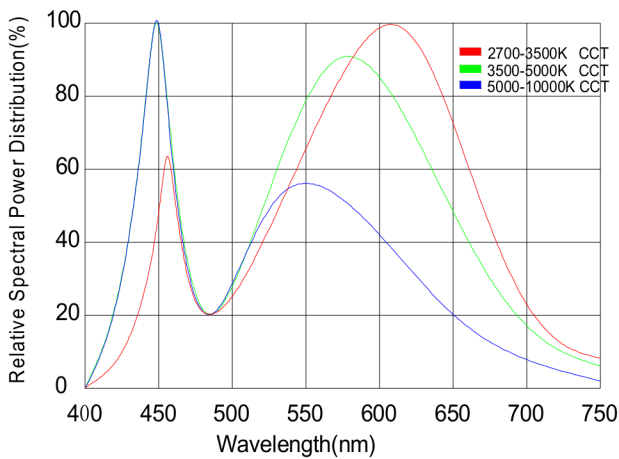
6-1. Relative Flux vs. Junction Temperature (If = 350 mA)  
White, Royal Blue, Blue, Green



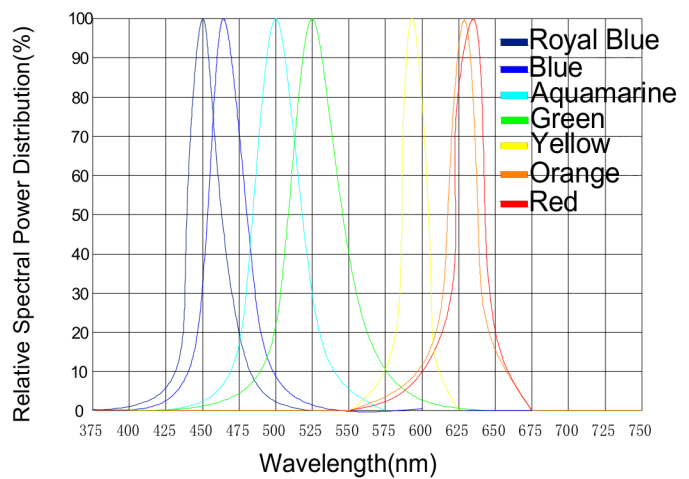
6-2. Relative Flux vs. Junction Temperature (If = 400 mA)  
Amber, Red



7. Typical white spectral distribution

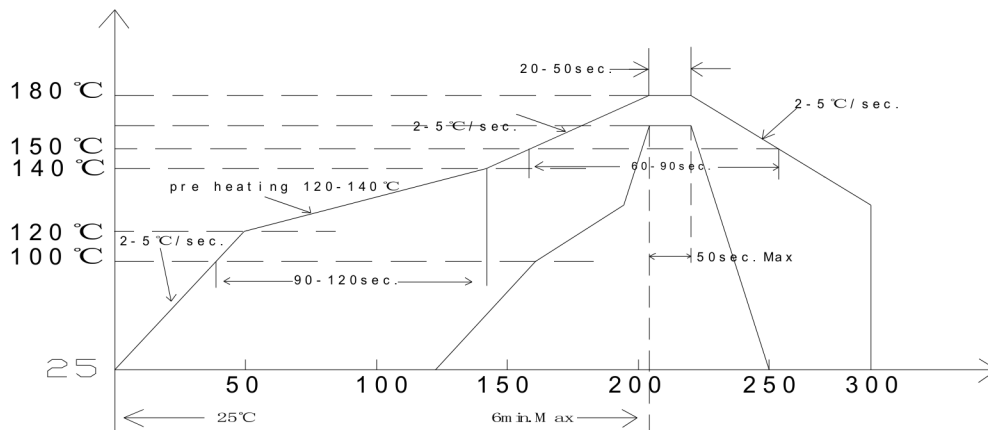


8. Relative Spectral Power Distribution



9. Reflow temperature time curve

Reflow Soldering Profile — Lead Free Solder



## Reliability Test Items And Conditions

Test Items	Test Condition	Test Hours Cyles	Sample Size	Ac/Re
DC Aging	Ta=25℃ IF=750mA	1000H	22	0/1
Hot and cold shock	-40℃/30min +100℃/30min	100Cycles	22	0/1
High Temperature Storage	Ta=100℃	1000H	22	0/1
High Temperature High Humidity	85℃/85%RH	1000H	22	0/1
Low TemPerature Storage	Ta=-40℃	1000H	22	0/1
ESD(HBM)	2000V HBM	1Time	10	0/1

## Criteria For Judging the Damage

Items	Symbol	Test Condition	Criteria For Judging Damage
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =750mA	Initial Data±10%
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	I <sub>R</sub> ≤10μA
Luminous Flux	φ <sub>v</sub>	I <sub>F</sub> =750mA	Average φ <sub>v</sub> degradation≤20% Single LED φ <sub>v</sub> degradation≤30%

## Soldering Condition

Reflow Soldering			Manual Welding	
	High temperature PC lens	Molding products	Temperature	Soldering time
Preheat	100-140°C	180-200°C	Highest 350°C	3ses once
Heatup time	120sec Max	120sec Max		
Peak temperature	180°C Max	260°C Max		
Condition of Soldering time	50sec Max	10sec Max		

\*Notes

Conventional PC lens products don't use reflow soldering.